

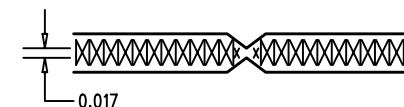
SHOWN FROM COMPONENT SIDE

REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		


SIZE	QTY	SYM	PLTD
0.015	97	+	PLTD
0.21	6	×	PLTD
0.035	312	□	PLTD
0.1	1	◇	NPLTD
0.07	4	⊠	NPLTD
0.125	8	A	PLTD
0.094	18	B	PLTD

NOTES : Unless Otherwise Specified

- MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD
THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS.
- FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE
ELECTRODEPOSITED TIN-LEAD COMPOSITION
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
- SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
- SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
- UNUSED SMD COMPONENTS SHOULD BE FREE OF SOLDER.
- SCORING:



- PLEASE LOOK AT THE README FILE FOR THE OTHER REQUIREMENTS.

APPROVALS			 LINEAR TECHNOLOGY 1630 McCarthy Blvd. Milpitas, CA 95035 PH: (408)432-1900	
	INIT	DATE		
DRAWN			TITLE: FABRICATION DRAWING I2C COMPACT PCI HOT SWAP CONTROLLER	
CHECK				
DESIGN	KIM T.	11-15-02		
ENGR	VICTOR F.	11-15-02		
			SIZE	REV.
			A	A
SCALE = NONE			DES- 0000	SHT 1 of 1